

Electronic Patent Application Fee Transmittal

Application Number:	10538306
Filing Date:	09-Jun-2005
Title of Invention:	Copper alloy for wiring, semiconductor device, method for forming wiring and method for manufacturing semiconductor device
First Named Inventor/Applicant Name:	Makoto Ueki
Filer:	Bruce Elliot Kramer/derrick hill
Attorney Docket Number:	Q88465

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130